

IN THE SPECIFICATION

Please amend the specification as follows:

Add the following paragraphs on page 3, line 25, after the description of FIG. 12:

FIG. 13A is a schematic cutaway view of a semiconductor package having a film placed on a backside of the package, according to an example embodiment.

FIG. 13B is a schematic cutaway view of a semiconductor package having a film placed on a backside of the package and having a device applying a force to the film and backside of the package, according to an example embodiment.

Add the following paragraph on page 6, line 4, before the paragraph describing FIG. 3:

FIG. 13A is a schematic cutaway view of a semiconductor package having a film placed on a backside of the package, according to an example embodiment. FIG. 13B is a schematic cutaway view of a semiconductor package having a film placed on a backside of the package and having a device applying a force to the film and backside of the package, according to an example embodiment. FIGs. 13A and 13B show one embodiment of forming the package as shown in FIG. 2C. Now referring to both FIGs. 13A and 13B, the semiconductor package includes a substrate 110, a die 120 attached to the substrate 110. The die 120 includes an inner layer dielectric (ILD) layer 121 where the devices associated with the die 120 are formed on a wafer before singulating the wafer into individual dies. An underfill material 130 is positioned between the die 110 and the substrate 120. The die 120 includes a frontside surface 122 near the substrate 110, a backside surface 124, and four sidewall surfaces 126, 127, 128 and one not shown. In some embodiments, the molding material or molding compound. A film 1300 is placed on the backside surface 124 of the semiconductor package. As shown in FIG. 13B, the film 1300, in some embodiments, is compressed by a device 1310 which places a compression force on the film. The film 1300 substantially prevents the second material or encapsulant from being applied to the backside surface 124 of the semiconductor package. The film is removed to

yield the structure shown in FIG. 2C. Of course, in some embodiments, the device 1310 for applying the compression force is removed as part of removing the film 1300.